TLE2027-Q1, TLE2037-Q1, TLE2027A-Q1, TLE2037A-Q1 EXCALIBUR LOW-NOISE HIGH-SPEED PRECISION OPERATIONAL AMPLIFIERS

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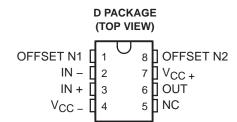
- Qualified for Automotive Applications
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Outstanding Combination of DC Precision and AC Performance:

Unity-Gain Bandwidth . . . 15 MHz Typ V_n 3.3 nV/\sqrt{Hz} at f = 10 Hz Typ, 2.5 nV/\sqrt{Hz} at f = 1 kHz Typ

V_{IO} 25 μV Max

A_{VD} ... 45 V/ μ V Typ With R_L = 2 kΩ, 19 V/ μ V Typ With R_I = 600 Ω

- Available in Standard-Pinout Small-Outline Package
- Output Features Saturation Recovery Circuitry
- Macromodels and Statistical information



description

The TLE20x7 and TLE20x7A contain innovative circuit design expertise and high-quality process control techniques to produce a level of ac performance and dc precision previously unavailable in single operational amplifiers. Manufactured using Texas Instruments state-of-the-art Excalibur process, these devices allow upgrades to systems that use lower-precision devices.

In the area of dc precision, the TLE20x7 and TLE20x7A offer maximum offset voltages of 100 μ V and 25 μ V, respectively, common-mode rejection ratio of 131 dB (typ), supply voltage rejection ratio of 144 dB (typ), and dc gain of 45 V/ μ V (typ).

The ac performance of the TLE2027 and TLE2037 is highlighted by a typical unity-gain bandwidth specification of 15 MHz, 55° of phase margin, and noise voltage specifications of 3.3 nV/ $\sqrt{\text{Hz}}$ and 2.5 nV/ $\sqrt{\text{Hz}}$ at frequencies of 10 Hz and 1 kHz, respectively. The TLE2037 and TLE2037A have been decompensated for faster slew rate (–7.5 V/ μ s, typical) and wider bandwidth (50 MHz). To ensure stability, the TLE2037 and TLE2037A should be operated with a closed-loop gain of 5 or greater.

ORDERING INFORMATION[†]

TA	V _{IO} max AT 25°C	PACKAGE [‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	05. \	0010 (D)	T	TLE2027AQDRQ1	2027AQ
4000 1- 40500	25 μV	SOIC (D)	Tape and reel	TLE2037AQDRQ1	2037AQ
-40°C to 125°C	400 1/	0010 (D)	T	TLE2027QDRQ1	2027Q1
	100 μV	SOIC (D)	Tape and reel	TLE2037QDRQ1	2037Q1

T For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

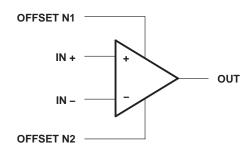
TLE2027-Q1, TLE2037-Q1, TLE2027A-Q1, TLE2037A-Q1 EXCALIBUR LOW-NOISE HIGH-SPEED PRECISION OPERATIONAL AMPLIFIERS

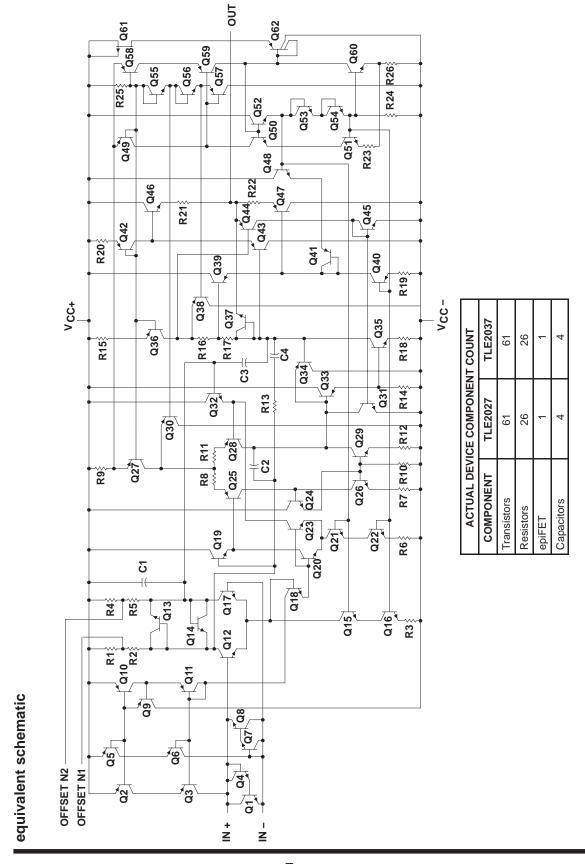
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description (continued)

Both the TLE20x7 and TLE20x7A are available in a wide variety of packages, including the industry-standard 8-pin small-outline version for high-density system applications. The Q-suffix devices are characterized for operation from -40° C to 125° C.

symbol





TLE2027-Q1, TLE2037-Q1, TLE2027A-Q1, TLE2037A-Q1 EXCALIBUR LOW-NOISE HIGH-SPEED PRECISION OPERATIONAL AMPLIFIERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC+} (see Note 1)	19 V
Supply voltage, V _{CC}	–19 V
Differential input voltage, V _{ID} (see Note 2)	±1.2 V
Input voltage range, V _I (any input)	V _{CC±}
Input current, I _I (each Input)	±1 mA
Output current, I _O	±50 mA
Total current into V _{CC+}	50 mA
Total current out of V _{CC}	
Duration of short-circuit current at (or below) 25°C (see Note 3)	Unlimited
Junction temperature, T _J	142°C
Operating free-air temperature range, T _A : Q suffix	–40°C to 125°C
Storage temperature range, T _{stq}	– 65°C to 150°C
Package thermal impedance, θ _{JA} (D Package) (0 LFPM) (see Note 4)	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D package	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V_{CC} + and V_{CC} -.
 - 2. Differential voltages are at IN+ with respect to IN –. Excessive current flows if a differential input voltage in excess of approximately ±1.2 V is applied between the inputs, unless some limiting resistance is used.
 - 3. The output may be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.
 - 4. The thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	MAX	UNIT
Supply voltage, V _{CC±}		±4	±19	V
Occurred the second sec	T _A = 25°C	-11	11	.,
Common-mode input voltage, V _{IC}	T _A = Full range [‡]	-10.2	10.2	V
Operating free-air temperature, T _A		-40	125	°C

Full range is -40°C to 125°C for Q-suffix devices.



TLE2027-Q1, TLE2037-Q1, TLE2027A-Q1, TLE2037A-Q1 EXCALIBUR LOW-NOISE HIGH-SPEED PRECISION OPERATIONAL AMPLIFIERS

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TLE20x7-Q1 electrical characteristics at specified free-air temperature, $V_{CC\pm}$ = ± 15 V (unless otherwise noted)

			_ +	TL	E20x7-0	21	TLE20x7A-Q1				
	PARAMETER	TEST CONDITIONS	T _A †	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
\/	Input offeet voltage		25°C		20	100		10	25	/	
VIO	Input offset voltage		Full range			200			105	μV	
α_{VIO}	Temperature coefficient of input offset voltage		Full range		0.4	1		0.2	1	μV/°C	
	Input offset voltage long-term drift (see Note 4)	$V_{IC} = 0$, $R_S = 50 \Omega$	25°C		0.006	1		0.006	1	μV/mo	
l. a	Input effect ourrent		25°C		6	90		6	90	~ ^	
IIO	Input offset current		Full range			150			150	nA	
lin	Input bias current		25°C		15	90		15	90	nA	
I _{IB}	input bias current		Full range			150			150	ПА	
.,	Common-mode input	5 50 0	25°C	–11 to 11	-13 to 13		–11 to 11	-13 to 13		.,	
VICR	voltage range	R _S = 50 Ω	Full range	-10.3 to 10.3			-10.4 to 10.4			V	
.,			25°C	10.5	12.9		10.5	12.9		V	
	Maximum positive peak output voltage swing	$R_L = 600 \Omega$	Full range	10			10				
VOM +		D. 2160	25°C	12	13.2		12	13.2			
		$R_L = 2 k\Omega$	Full range	11			11				
		D. 600 O	25°C	-10.5	-13		-10.5	-13		V	
V0.1	Maximum negative peak	R _L = 600 Ω	Full range	-10			-10				
VOM -	output voltage swing	$R_L = 2 k\Omega$	25°C	-12	-13.5		-12	-13.5			
		N_ = 2 K22	Full range	-11			-11				
		$V_O = \pm 11 \text{ V}, R_L = 2 \text{ k}\Omega$	25°C	5	45		10	45			
	Large-signal differential	$V_O = \pm 10 \text{ V}, R_L = 2 \text{ k}\Omega$	Full range	2.5			3.5				
A_{VD}	voltage amplification	$V_O = \pm 10 \text{ V}, R_L = 1 \text{ k}\Omega$	25°C	3.5	38		8	38		V/µV	
	3 1	VO = ± 10 V, IXL = 1 K22	Full range	1.8			2.2				
		$V_0 = \pm 10 \text{ V}, R_L = 600 \Omega$	25°C	2	19		5	19			
Ci	Input capacitance		25°C		8			8		pF	
z _O	Open-loop output impedance	IO = 0	25°C		50			50		Ω	
CMRR	Common-mode rejection	V _{IC} = V _{ICR} min,	25°C	100	131		117	131		dВ	
CIVIKK	ratio	$R_S = 50 \Omega$	Full range	96			113			dB	
kovo	Supply-voltage rejection	$V_{CC\pm} = \pm 4 \text{ V to } \pm 18 \text{ V},$ $R_S = 50 \Omega$	25°C	94	144		110	144		dB	
ksvr	ratio ($\Delta V_{CC\pm} / \Delta V_{IO}$)	$V_{CC\pm} = \pm 4 \text{ V to } \pm 18 \text{ V},$ $R_S = 50 \Omega$	Full range	90			105				
loc	Supply current	V _O = 0, No load	25°C		3.8	5.3		3.8	5.3	mΔ	
ICC	очрріу синені	VO = 0, INU IUAU	Full range			5.6			5.6	mA	

[†] Full range is -40°C to 125°C.

NOTE 4: Typical values are based on the input offset voltage shift observed through 168 hours of operating life test at $T_A = 150^{\circ}C$ extrapolated to $T_A = 25^{\circ}C$ using the Arrhenius equation and assuming an activation energy of 0.96 eV.



TLE2027-Q1, TLE2037-Q1, TLE2027A-Q1, TLE2037A-Q1 EXCALIBUR LOW-NOISE HIGH-SPEED PRECISION OPERATIONAL AMPLIFIERS

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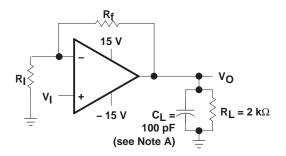
TLE20x7-Q1 operating characteristics at specified free-air temperature, $V_{CC\,\pm}$ = ± 15 V, T_A = 25°C (unless otherwise specified)

PARAMETER		TEST CONDITI	TI	_E20x7-Q1		Τl				
		TEST CONDITI	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
	$R_L = 2 k\Omega$,	TLE2027	1.7	2.8		1.7	2.8			
		C _L = 100 pF, See Figure 1	TLE2037	6	7.5		6	7.5		
SR	Slew rate at unity gain	$R_L = 2 k\Omega$, $C_L = 100 pF$,	TLE2027	1			1			V/μs
		$T_A = -55^{\circ}C$ to 125°C, See Figure 1	TLE2037	4.4			4.4			
\ <u></u>	Equivalent input noise	$R_S = 20 \Omega$,	f = 10 Hz		3.3	8		3.3	4.5	nV/√ Hz
Vn	voltage (see Figure 2)	$R_S = 20 \Omega$,	f = 1 kHz		2.5	4.5		2.5	3.8	IIV/ \ITZ
V _{N(PP)}	Peak-to-peak equivalent input noise voltage	f = 0.1 Hz to 10 Hz			50	250		50	130	nV
	Equivalent input noise	f = 10 Hz			10			10		- A / /I I=
^I n	current	f = 1 kHz			0.8			0.8		pA/√Hz
		V _O = +10 V, A _{VD} = 1, See Note 5	TLE2027		<0.002			<0.002		0,
THD	Total harmonic distortion	V _O = +10 V, A _{VD} = 5, See Note 5	TLE2037		<0.002			<0.002		%
Б	Unity-gain bandwidth	$R_L = 2 k\Omega$,	TLE2027	7	13		9	13		NAL I-
B ₁	(see Figure 3)	C _L = 100 pF	TLE2037	35	50		35	50		MHz
D	Maximum output-swing	D. 210	TLE2027		30			30		ld la
ВОМ	bandwidth	$R_L = 2 k\Omega$	TLE2037		80			80		kHz
φ.	Phase margin at unity	$R_L = 2 k\Omega$,	TLE2027		55			55		0
Φm	gain (see Figure 3)	C _L = 100 pF	TLE2037		50		_	50		

NOTE 5: Measured distortion of the source used in the analysis was 0.002%.

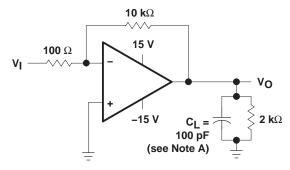


PARAMETER MEASUREMENT INFORMATION



NOTE A: C_L includes fixture capacitance.

Figure 1. Slew-Rate Test Circuit



NOTE A: C_L includes fixture capacitance.

Figure 3. Unity-Gain Bandwidth and Phase-Margin Test Circuit (TLE2027 Only)

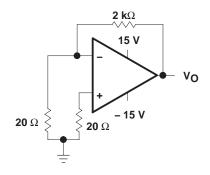
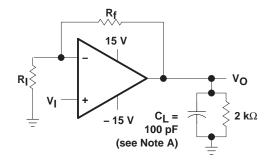


Figure 2. Noise-Voltage Test Circuit



NOTES: A. C_L includes fixture capacitance. B. For the TLE2037 and TLE2037A,

AVD must be ≥ 5 .

Figure 4. Small-Signal Pulse-Response Test Circuit

TLE2027-Q1, TLE2037-Q1, TLE2027A-Q1, TLE2037A-Q1 EXCALIBUR LOW-NOISE HIGH-SPEED PRECISION OPERATIONAL AMPLIFIERS

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typical values

Typical values presented in this data sheet represent the median (50% point) of device parametric performance.

initial estimates of parameter distributions

In the ongoing program of improving data sheets and supplying more information to our customers, Texas Instruments has added an estimate of not only the typical values, but also the spread around these values. These are in the form of distribution bars that show the 95% (upper) points and the 5% (lower) points from the characterization of the initial wafer lots of this new device type (see Figure 5). The distribution bars are shown at the points where data was actually collected. The 95% and 5% points are used instead of ± 3 sigma, since some of the distributions are not true Gaussian distributions.

The number of units tested and the number of different wafer lots used are on all of the graphs where distribution bars are shown. As noted in Figure 5, there were a total of 835 units from two wafer lots. In this case, there is a good estimate for the within-lot variability and a possibly poor estimate of the lot-to-lot variability. This is always the case on newly released products, since there can only be data available from a few wafer lots.

The distribution bars are not intended to replace the minimum and maximum limits in the electrical tables. Each distribution bar represents 90% of the total units tested at a specific temperature. While 10% of the units tested fell outside any given distribution bar, this should not be interpreted to mean that the same individual devices fell outside every distribution bar.

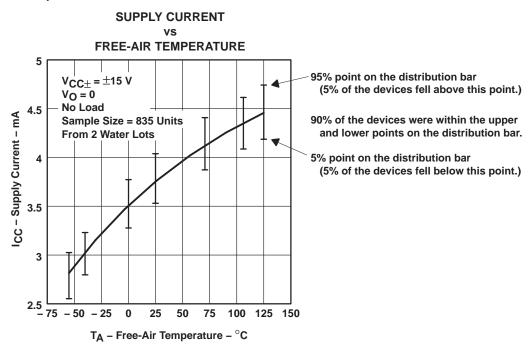


Figure 5. Sample Graph With Distribution Bars



TLE2027-Q1, TLE2037-Q1, TLE2027A-Q1, TLE2037A-Q1 EXCALIBUR LOW-NOISE HIGH-SPEED PRECISION OPERATIONAL AMPLIFIERS SGLS202A - OCTOBER 2003 - REVISED OCTOBER 2006

TYPICAL CHARACTERISTICS

Table of Graphs

			FIGURE
V _{IO}	Input offset voltage	Distribution	6, 7
ΔV_{IO}	Input offset voltage change	vs Time after power on	8, 9
IIO	Input offset current	vs Free-air temperature	10
I _{IB}	Input bias current	vs Free-air temperature vs Common-mode input voltage	11 12
Ц	Input current	vs Differential input voltage	13
VO(PP)	Maximum peak-to-peak output voltage	vs Frequency	14, 15
V _{OM}	Maximum (positive/negative) peak output voltage	vs Load resistance vs Free-air temperature	16, 17 18, 19
AVD	Large-signal differential voltage amplification	vs Supply voltage vs Load resistance vs Frequency vs Free-air temperature	20 21 22 – 25 26
z _O	Output impedance	vs Frequency	27
CMRR	Common-mode rejection ratio	vs Frequency	28
ksvr	Supply-voltage rejection ratio	vs Frequency	29
los	Short-circuit output current	vs Supply voltage vs Elapsed time vs Free-air temperature	30, 31 32, 33 34, 35
Icc	Supply current	vs Supply voltage vs Free-air temperature	36 37
	Voltage-follower pulse response	Small signal Large signal	38, 40 39, 41
Vn	Equivalent input noise voltage	vs Frequency	42
	Noise voltage (referred to input)	Over 10-second interval	43
B ₁	Unity-gain bandwidth	vs Supply voltage vs Load capacitance	44 45
	Gain bandwidth product	vs Supply voltage vs Load capacitance	46 47
SR	Slew rate	vs Free-air temperature	48, 49
Фт	Phase margin	vs Supply voltage vs Load capacitance vs Free-air temperature	50, 51 52, 53 54, 55
	Phase shift	vs Frequency	22 – 25



DISTRIBUTION INPUT OFFSET VOLTAGE

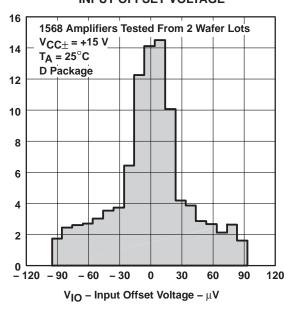


Figure 6

TIME AFTER POWER ON 12 10 10 50 Amplifiers Tested From 2 Wafer Lots VCC± = ±15 V TA = 25°C D Package

INPUT OFFSET VOLTAGE CHANGE

Figure 7

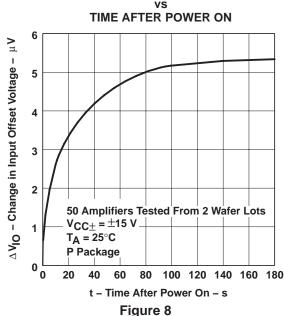
0

0

10

20

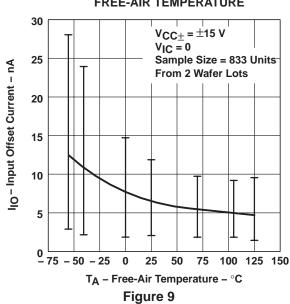
INPUT OFFSET VOLTAGE CHANGE



INPUT OFFSET CURRENT† vs FREE-AIR TEMPERATURE

t - Time After Power On - s

60

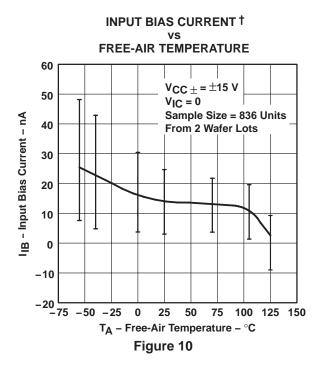


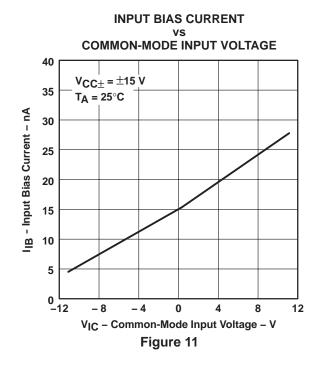
[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

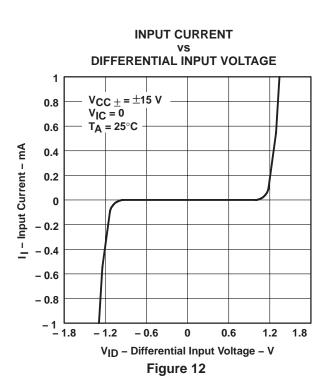


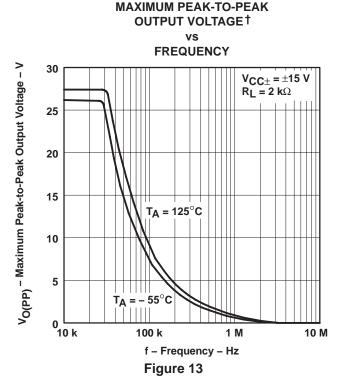
Percentage of Amplifiers - %

TYPICAL CHARACTERISTICS









TLE2027

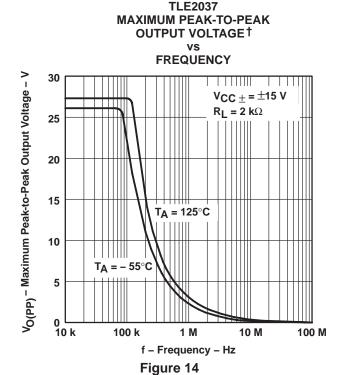
[†]Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



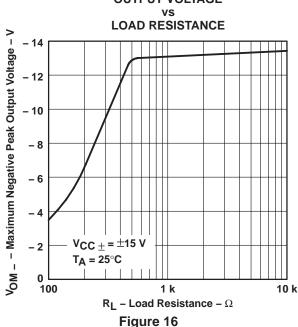
TLE2027-Q1, TLE2037-Q1, TLE2027A-Q1, TLE2037A-Q1 **EXCALIBUR LOW-NOISE HIGH-SPEED** PRECISION OPERATIONAL AMPLIFIERS

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TYPICAL CHARACTERISTICS







OUTPUT VOLTAGE vs LOAD RESISTANCE V_{OM +} - Maximum Positive Peak Output Voltage - V 12 10 8 6

 $V_{CC\pm} = \pm 15 V$

T_A = 25°C

2

100

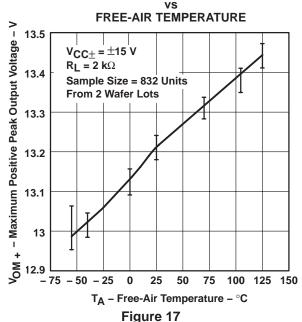
MAXIMUM POSITIVE PEAK

Figure 15 **MAXIMUM POSITIVE PEAK OUTPUT VOLTAGE**†

1 k

 R_L – Load Resistance – Ω

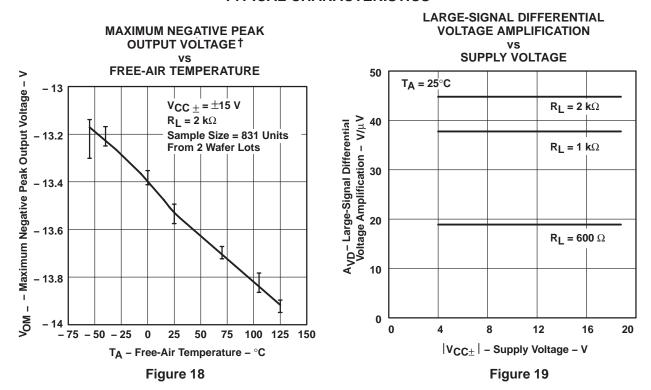
10 k



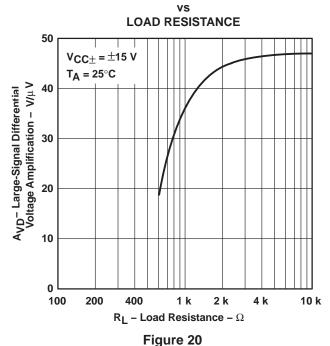
[†]Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



TYPICAL CHARACTERISTICS



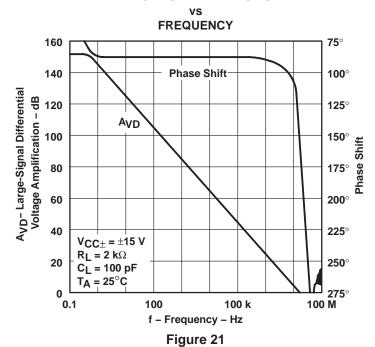
LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION



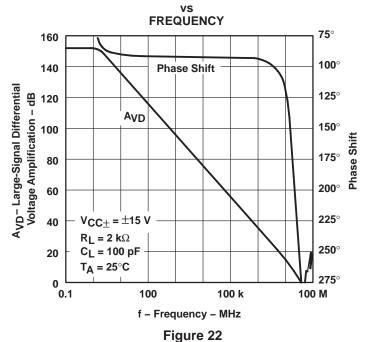
[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



TLE2027 LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE SHIFT



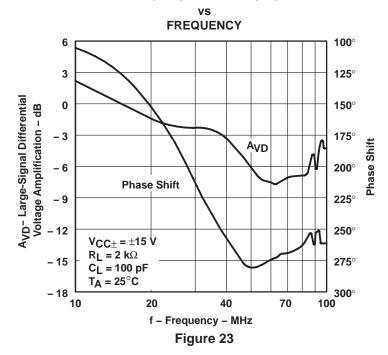
TLE2037 LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE SHIFT



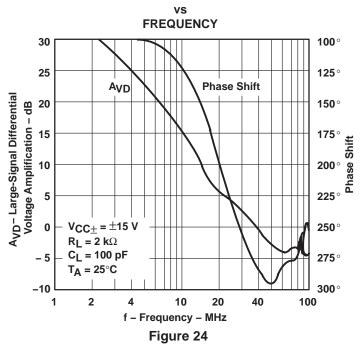


TYPICAL CHARACTERISTICS

TLE2027 LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE SHIFT

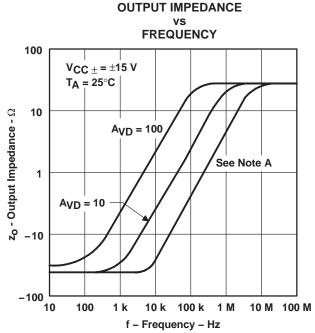


TLE2037 LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE SHIFT





LARGE-SIGNAL DIFFERENTIAL **VOLTAGE AMPLIFICATION**† vs FREE-AIR TEMPERATURE 60 $V_{CC \pm} = \pm 15 \text{ V}$ $A_{VD}-$ Large-Signal Differential Voltage Amplification – $V/\mu V$ 50 $R_L = 2 k\Omega$ $R_L = 1 k\Omega$ 30 **-75 -50** -25 25 50 75 100 125 150

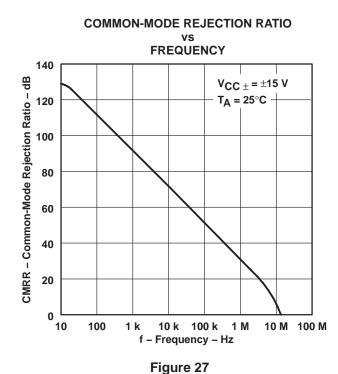


NOTE A: For this curve, the TLE2027 is $A_{VD} = 1$ and the TLE2037 is $A_{VD} = 5$.

Figure 25

T_A - Free-Air Temperature - °C





SUPPLY-VOLTAGE REJECTION RATIO

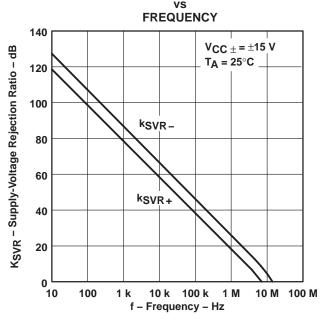


Figure 28

[†]Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



SHORT-CIRCUIT OUTPUT CURRENT **SUPPLY VOLTAGE** -42 $V_{ID} = 100 \text{ mV}$ IOS - Short-Circuit Output Current - mA $V_{O} = 0$ -40 T_A = 25°C P Package -38 -36 -34 -32 -30 8 10 12 14 0 $|V_{CC\pm}|$ – Supply Voltage – V

Figure 29

SHORT-CIRCUIT OUTPUT CURRENT vs ELAPSED TIME

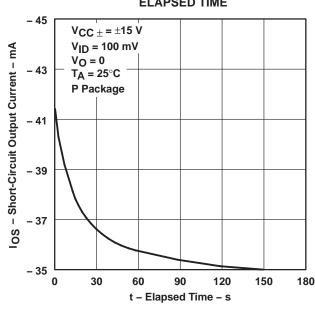


Figure 31

SHORT-CIRCUIT OUTPUT CURRENT VS SUPPLY VOLTAGE

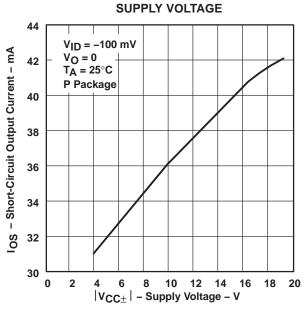


Figure 30

SHORT-CIRCUIT OUTPUT CURRENT vs

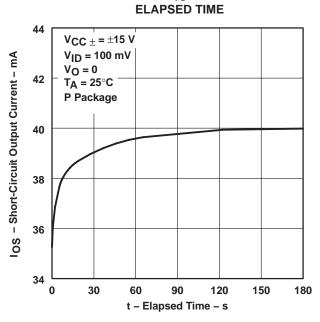
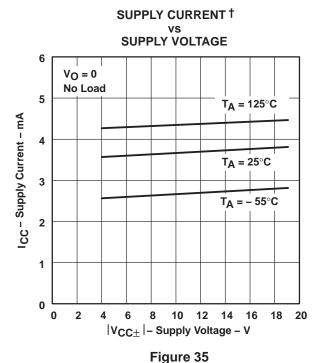


Figure 32

SHORT-CIRCUIT OUTPUT CURRENT † FREE-AIR TEMPERATURE - 48 $V_{CC \pm} = \pm 15 V$ IOS - Short-Circuit Output Current - mA $V_{ID} = 100 \text{ mV}$ - 44 $V_O = 0$ P Package - 40 - 36 - 32 - 28 - 75 - 50 - 25 50 75 100 T_A - Free-Air Temperature - °C

Figure 33



SHORT-CIRCUIT OUTPUT CURRENT †

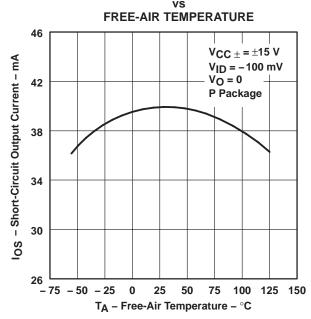


Figure 34

SUPPLY CURRENT † vs FREE-AIR TEMPERATURE

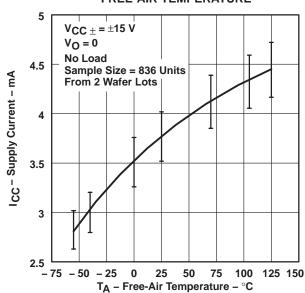


Figure 36

[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



TLE2027

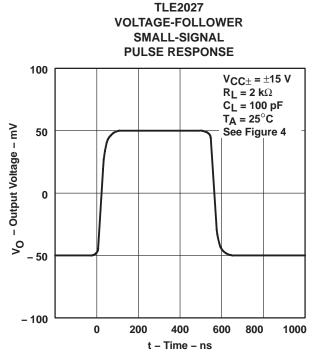
VOLTAGE-FOLLOWER

TYPICAL CHARACTERISTICS

- 15

0

5



LARGE-SIGNAL PULSE RESPONSE

15 $V_{CC\pm} = \pm 15 V$ $R_{L} = 2 k\Omega$ $C_{L} = 100 \text{ pF}$ $T_{A} = 25^{\circ}\text{C}$ See Figure 1

- 10

Figure 37



15

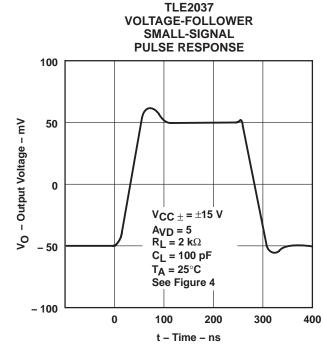
20

25

10

t – Time – μ s

Figure 38



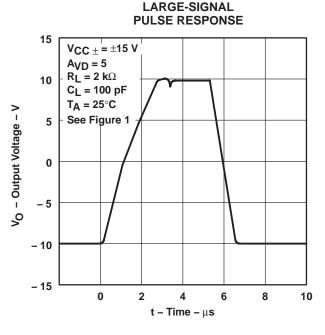


Figure 39



EQUIVALENT INPUT NOISE VOLTAGE

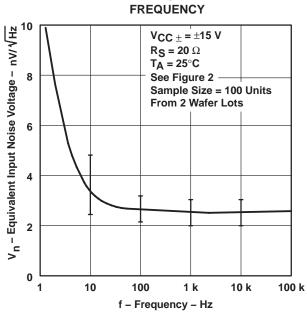


Figure 41

NOISE VOLTAGE (REFERRED TO INPUT) OVER A 10-SECOND INTERVAL

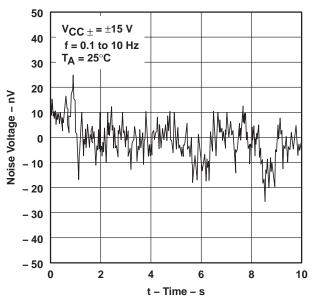
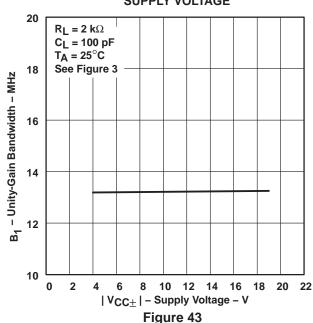
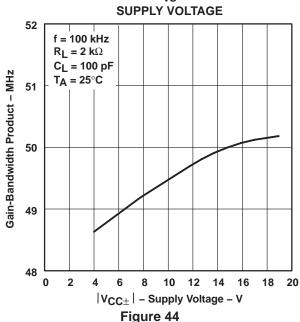


Figure 42

TLE2027 UNITY-GAIN BANDWIDTH VS SUPPLY VOLTAGE

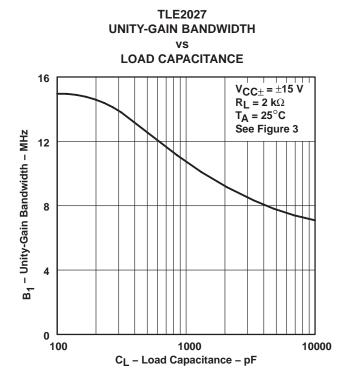


TLE2037 GAIN-BANDWIDTH PRODUCT vs





TYPICAL CHARACTERISTICS



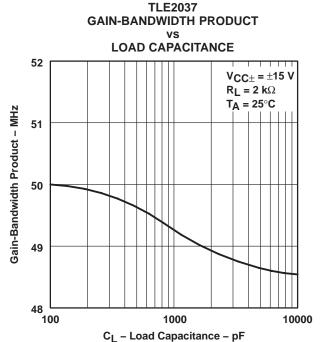


Figure 45

TLE2027

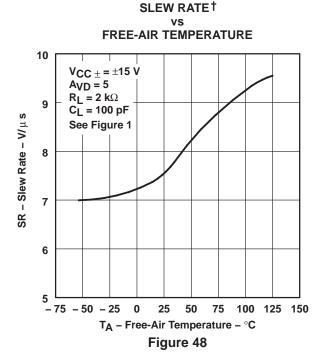
SLEW RATE† ٧S FREE-AIR TEMPERATURE 3 2.8 SR - Slew Rate - V/µs 2.6 2.4 $V_{CC\pm} = \pm 15 V$ $A_{VD} = 1$ 2.2 $R_L = 2 k\Omega$ $C_{L} = 100 pF$ See Figure 1 -75 - 50 - 2525 50 75 100 125 150

 T_A – Free-Air Temperature – $^{\circ}C$

Figure 47

Figure 46

TLE2037



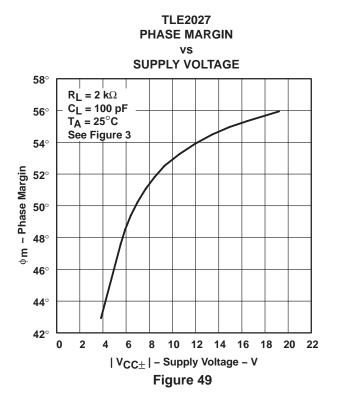
†Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

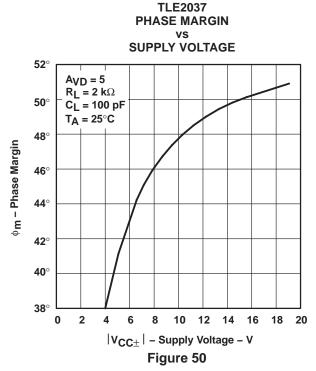


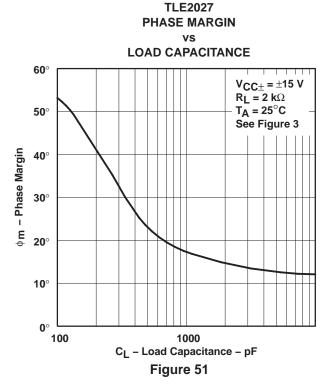
TLE2027-Q1, TLE2037-Q1, TLE2027A-Q1, TLE2037A-Q1 EXCALIBUR LOW-NOISE HIGH-SPEED PRECISION OPERATIONAL AMPLIFIERS

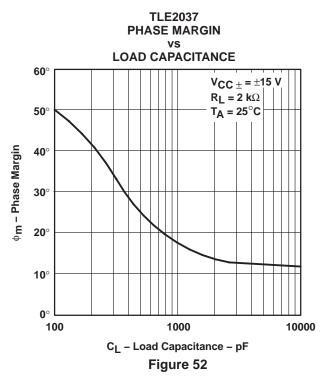
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TYPICAL CHARACTERISTICS







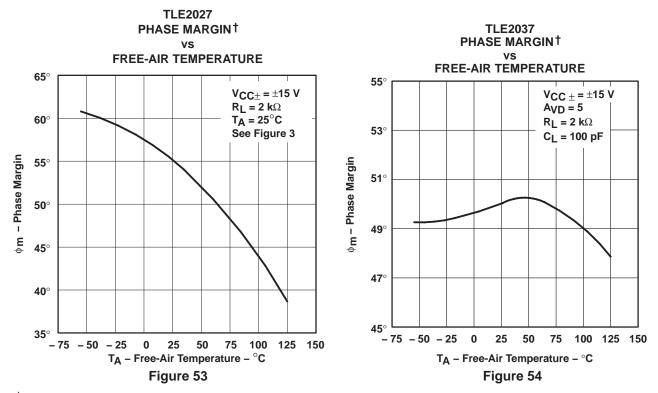




TLE2027-Q1, TLE2037-Q1, TLE2027A-Q1, TLE2037A-Q1 EXCALIBUR LOW-NOISE HIGH-SPEED PRECISION OPERATIONAL AMPLIFIERS

SGLS202A - OCTOBER 2003 - REVISED OCTOBER 2006

TYPICAL CHARACTERISTICS



† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

APPLICATION INFORMATION

input offset voltage nulling

The TLE2027 and TLE2037 series offers external null pins that can be used to further reduce the input offset voltage. The circuits of Figure 55 can be connected as shown if the feature is desired. If external nulling is not needed, the null pins may be left disconnected.

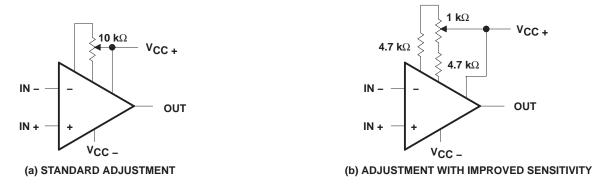


Figure 55. Input Offset Voltage Nulling Circuits

voltage-follower applications

The TLE2027 circuitry includes input-protection diodes to limit the voltage across the input transistors; however, no provision is made in the circuit to limit the current if these diodes are forward biased. This condition can occur when the device is operated in the voltage-follower configuration and driven with a fast, large-signal pulse. It is recommended that a feedback resistor be used to limit the current to a maximum of 1 mA to prevent degradation of the device. Also, this feedback resistor forms a pole with the input capacitance of the device. For feedback resistor values greater than 10 k Ω , this pole degrades the amplifier phase margin. This problem can be alleviated by adding a capacitor (20 pF to 50 pF) in parallel with the feedback resistor (see Figure 56).

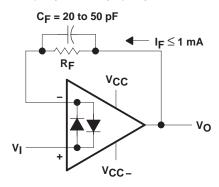


Figure 56. Voltage Follower



APPLICATION INFORMATION

macromodel information

Macromodel information provided was derived using Microsim *Parts*™, the model generation software used with Microsim *PSpice*™. The Boyle macromodel (see Note 6) and subcircuit in Figure 57, Figure 58, and Figure 59 were generated using the TLE20x7 typical electrical and operating characteristics at 25°C. Using this information, output simulations of the following key parameters can be generated to a tolerance of 20% (in most cases):

- Maximum positive output voltage swing
- Maximum negative output voltage swing
- Slew rate
- Quiescent power dissipation
- Input bias current
- Open-loop voltage amplification

- Gain-bandwidth product
- Common-mode rejection ratio
- Phase margin
- DC output resistance
- AC output resistance
- Short-circuit output current limit

NOTE 6: G. R. Boyle, B. M. Cohn, D. O. Pederson, and J. E. Solomon, "Macromodeling of Integrated Circuit Operational Amplifiers", IEEE Journal of Solid-State Circuits, SC-9, 353 (1974).

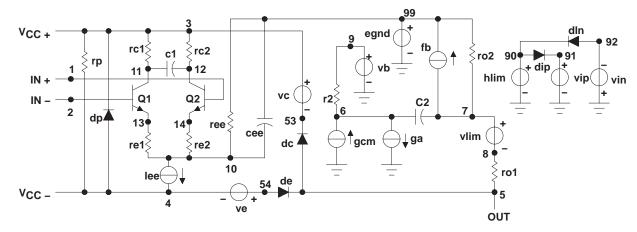


Figure 57. Boyle Macromodel

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APPLICATION INFORMATION

macromodel information (continued)

.subckt	TLE202	7 1 2	3 4	5		q2	12	1	14	qx
*						r2	6	9	100	.0E3
c1	11	12	4.0	03E-	12	rc1	3	11	530	.5
c2	6	7	20.	00E-	12	rc2	3	12	530	.5
dc	5	53	dz			re1	13	10	-39	3.2
de	54	5	dz			re2	14	10	-39	3.2
dlp	90	91	dz			ree	10	99	3.5	71E6
dln	92	90	dx			ro1	8	5	25	
dp	4	3	dz			ro2	7	99	25	
egnd	99	0	pol	y(2)	(3,0)	rp	3	4	8.0	13E3
(4,0) 0	5 .5					vb	9	0	dc	0
fb	7	99	pol	y(5)	vb vc	VC	3	53	dc	2.400
ve vlp v	ln 0 9	54.8E	6 -1	E9 1	E9 1E9	ve	54	4	dc	2.100
-1E9						vlim	7	8	dc	0
ga	6	0	11	12		vlp	91	0	dc	40
2.062E-3						vln	0	92	dc	40
gcm	0	6	10	99		.modeldx	•			,
531.3E-1	.2					.modelqx		[s=80	0.0E-	18
iee	10	4			01E-6	Bf = 7.000I	Ξ3)			
hlim	90	0	vli	m 1K		.ends				
q1	11	2	13	dх						

Figure 58. TLE2027 Macromodel Subcircuit

.subckt *	TLE203	7 1	2 3 4 5	q2 r2	12 6	1 9	14 100	qz .0E3
c1	11	12	4.003E-12	rc1	3	11	471	.5
c2	6	7	7.500E-12	rc2	3	12	471	.5
dc	5	53	dz	re1	13	10	A44	8
de	54	5	dz	re2	14	10	A44	8
dlp	90	91	dz	ree	10	99	3.5	55E6
dln	92	90	dx	ro1	8	5	25	
dp	4	3	dz	ro2	7	99	25	
egnd	99	0	poly(2) (3,0)	rp	3	4	8.0	13E3
(4)	,0)0	. 5	.5	vb	9	0	dc	0
fb	7	99	poly(5) vb vc	VC	3	53	dc	2.400
ve	vip vl	n 0	923.4E6 A800E6	ve	54	4	dc	2.100
800	DE6 800	E6 A	.800E6	vlim	7	8	dc	0
ga	6	0	11 12 2.121E-3	vlp	91	0	dc	40
gcm	0	6	10 99 597.7E-12	vln	0	92	dc	40
iee	10	4	dc 56.26E-6	.model	dxD(Is=800.0E-18)			
hlim	90	0	vlim 1K	.model	qxN1	PN(Is	=800	.0E-18
q1	11	2	13 qx	Bf=7.	031E3)		
				.ends				

Figure 59. TLE2037 Macromodel Subcircuit



PACKAGE OPTION ADDENDUM

www.ti.com 26-Mar-2010

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TLE2037AQDRG4Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLE2037AQDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLE2037QDRG4Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLE2037QDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF TLE2037-Q1, TLE2037A-Q1:

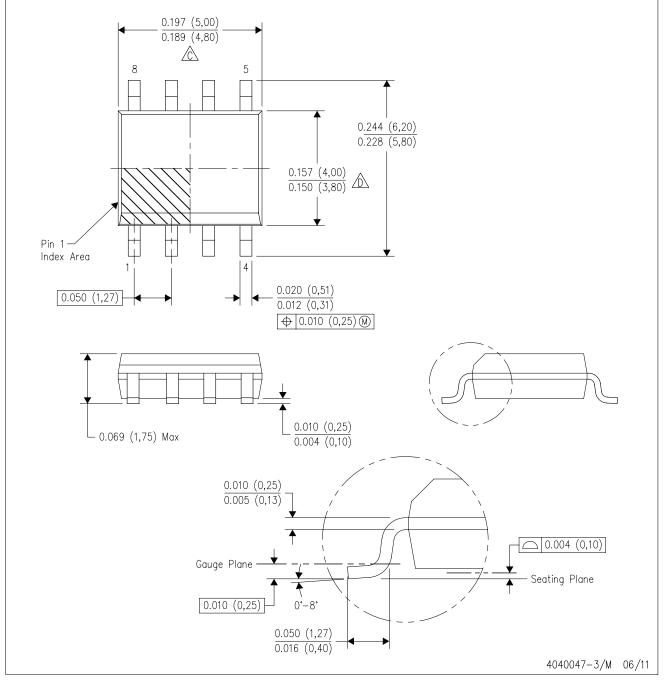
Catalog: TLE2037, TLE2037A

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



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